MA3J742 (MA742)

Silicon epitaxial planar type

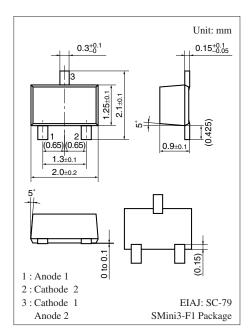
For switching

■ Features

- Two MA3X716 (MA716) is contained in one package (series connection)
- Forward voltage V_F, optimum for low voltage rectification
- Optimum for high frequency rectification because of its short reverse recovery time t_{rr}

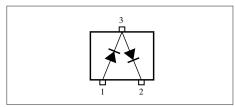
■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter		Symbol	Rating	Unit
Reverse voltage		V_R	30	V
Maximum peak reverse voltage		V_{RM}	30	V
Forward current	Single	I_{F}	30	mA
	Series		20	
Peak forward current	Single	I_{FM}	150	mA
	Series		110	
Junction temperature		T _j	125	°C
Storage temperature		T_{stg}	-55 to +125	°C



Marking Symbol: M1U

Internal Connection



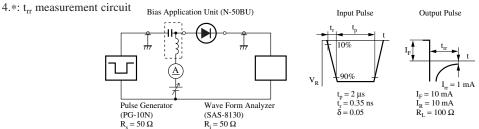
■ Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	V_{F1}	$I_F = 1 \text{ mA}$			0.4	V
	V_{F2}	$I_F = 30 \text{ mA}$			1.0	
Reverse current	I_R	$V_R = 30 \text{ V}$			1	μΑ
Terminal capacitance	C _t	$V_R = 1 \text{ V, } f = 1 \text{ MHz}$		1.5		pF
Reverse recovery time *	t _{rr}	$I_F = I_R = 10 \text{ mA}$ $I_{rr} = 1 \text{ mA}, R_{L} = 100 \Omega$		1.0		ns
						64
Detection efficiency	η	$V_{IN} = 3 V_{(peak)}$, $f = 30 \text{ MHz}$ $R_L = 3.9 \text{ k}\Omega$, $C_L = 10 \text{ pF}$		65		%

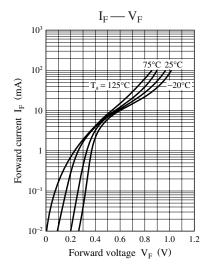
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

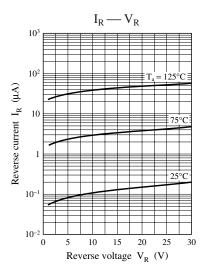
2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

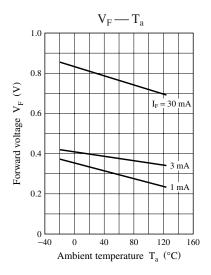
fep3. Absolute frequency of input and output is 2 GHz.

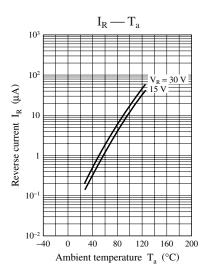


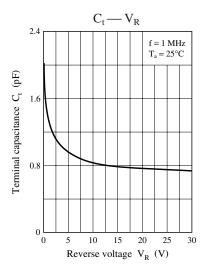
Note) The part number in the parenthesis shows conventional part number.











2 SKH00056CED

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